



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Hall et al.

Patent No.: 7,116,000 B2

Issued: October 3, 2006

For: UNDERFILLED, ENCAPSULATED SEMICONDUCTOR DIE ASSEMBLIES AND METHODS OF FABRICATION

Attorney Docket No.: 2269-5165.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

August 30, 2007

Date

Signature

Shawnee MacDonald

Name (Type/Print)

LETTER MAKING ERRORS OF RECORD

Certificate

SEP 2 1 2007

of Correction

Sir:

Please make the following errors of record in the file history of the above-referenced Letters Patent:

In the specification:

Commissioner for Patents

Alexandria, VA 22313-1450

P.O. Box 1450

| COLUMN 6, | LINE 51, | change "adhesive element 130" to |
|-----------|--------------|---|
| | | adhesive elements 130 |
| COLUMN 6, | LINE 57, | after "materials" and before "T693-R3001EX- |
| | | V3" insertare |
| COLUMN 6, | LINE 64, | after "than" and before "particle" insert the |
| COLUMN 6, | LINE 66, | after "enhancing" and before "flow" insertthe |
| COLUMN 7, | LINE 27, | delete "the"; and change "substrate 110" to |
| | | substrates |
| COLUMN 8, | LINE 46, | change "provides" toprovide |
| COLUMN 8, | LINES 47-48, | change "adhesive element 130" to |
| | | adhesive elements 130 |
| COLUMN 9, | LINE 60, | delete "a" at the beginning of line |
| | | |

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Respectfully submitted,

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Date: August 30, 2007

JJG/df/slm Document in ProLaw